

**Manufacturing
Procedure**

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Masking**Revision**

A

Description of Change

Initial Release

Date Effective


05/13/99

Author

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Originator


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Title:

Masking**1.0 Purpose**

- 1.1 The purpose of this document is to ensure the quality and process control in masking process.

2.0 Scope

- 2.1 This procedure applies to the masking process for closed-loop and open-loop water wash processes.
- 2.2 The procedure applies to masking for wave solder process.

3.0 Reference

- 3.1 SOP22 ESD procedure
- 3.2 SOP11 First Article Procedure
- 3.3 IPC-A-610 Acceptability of Electronic Assemblies
- 3.4 MSDS and technical data sheet for peelable masks

4.0 Definitions

- 4.1 PCA: Printed Circuit Assembly
- 4.2 TEK-MATE Lineboard: A board made by TEK-Mate with conductive foams attached to it.

5.0 Responsibilities

- 5.1 It is everyone's responsibility to follow the ESD and safety rules described in this procedure.
- 5.2 Operators are responsible for following the documentation to ensure quality product.
- 5.3 The area supervisor shall follow SOP11-First Article and will assist operators as necessary.

6.0 Equipment

- 6.1 Lineboards - They are put on the line conveyor or on the working table.

7.0 Materials

- 7.1 PCAs
- 7.2 Visual aids or proper customer documentation.
- 7.3 Masking materials:
- 7.3.1 Peelable mask TC 530.

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7.4 Kapton Tape

7.5 High temperature masking tape, dots

8.0 Records

8.1 The total retention period for the documents listed by Meritronics Inc. is indicated on the Master Forms Listing under the column heading, Record Retention. When the records are no longer in an active status they will be forwarded to Document Control and filed/maintained in accordance with SOP 29.

9.0 Procedure

9.1 Safety

9.1.1 Wash hands after handling the material.

9.2 Get MPI documentation detailing where to apply masking.

9.3 Keep hands free of oil and grease prior to operation.

9.4 Cover the gold fingers both sides and required places with Kapton tape.

9.5 Transfer the masking material into a dispensing bottle for better control.

9.6 Cover the mounting holes or screw heads fully with masking material.

9.7 Do not cover solder joints with masking material. If there is a spill or mistake on the boards, don't wipe it off. Wait until it is cured and remove it.